ETR08001-004c

### Charge Pump Voltage Inverter IC

### GENERAL DESCRIPTION

The XC6351A series are charge pump voltage inverter ICs that have 4 MOSFETs built in. Since highly efficient negative voltages can be generated with only 2 external capacitors connected, GaAs bias power supplies & OpAmp's negative power supplies etc., can be easily accommodated on a standard PCB.

A mini-molded, SOT-26 and USP-6B packages provides for space saving and makes high density mounting possible. Low power consumption and high efficiency make this series perfect for use with battery operated applications.

Since the IC's operations stop when output is shutdown via the CE (chip enable) function, total power consumption reduction is possible in applications which use this IC.

### ■ APPLICATIONS

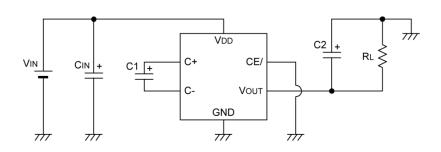
Negative power supplies

- Power supplies for Opamp
- Cellular and portable phones
- Miniature LCD panels
- PDAs
- Various battery powered systems

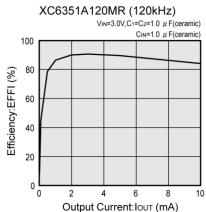
#### ■FEATURES

Operating Voltage Range	: 1.2V ~ 5.0V
<b>Oscillation Frequency</b>	: 120kHz
	: 35kHz (custom)
Low Supply Current	: 310µA (TYP.)
	: 100µA (35kHz custom TYP.)
High Efficiency	: 90% (TYP.) ( RL = 2kΩ)
Stand-by Current	: 2.0µA (MAX.)
CE(Chip Enable) Function	
<b>Operating Ambient Temperature</b>	: -30°C ~ 80°C
Packages	: SOT-26 ,USP-6B
Environmentally Friendly	: EU RoHS Compliant, Pb Free

### ■ TYPICAL APPLICATION CIRCUIT

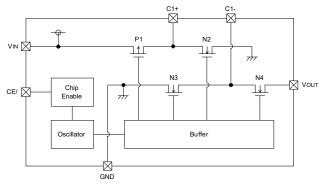


### ■ TYPICAL PERFORMANCE CHARACTERISTICS



# XC6351A Series

# BLOCK DIAGRAM



# ■PRODUCT CLASSIFICATION

#### Ordering Information

XC6351A (12345-6)(\*1)

DESIGNATOR	DESCRIPTION	SYMBOL	DESCRIPTION				
100	(1)2)3 Oscillation Frequency		120kHz				
(1/2/3)	Oscillation Frequency	035	35kHz (custom)				
45-6	Packages		SOT-26 (3,000pcs/Reel)				
40-0	Taping Type	DR-G	USP-6B (3,000pcs/Reel)				

Note:

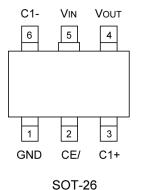
alternately:

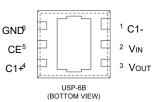
P1 & N3 ON: N2 & N4 OFF

P1 & N3 OFF: N2 & N4 ON

(\*1) The "-G" suffix indicates that the products are Halogen and Antimony free as well as being fully EU RoHS compliant.

# ■ PIN CONFIGURATION





\*The dissipation pad for the USP-6B package should be solder-plated in recommended mount pattern and metal masking so as to enhance mounting strength and heat release.

1. In operation, the following conditions will be repeated

The output pin VOUT will be connected to GND.

2. In standby mode, P1, N3 & N4 will be ON and N2 will be OFF.

If the pad needs to be connected to other pins, it should be connected to the VIN (No. 2) pin.

### ■ PIN ASSIGNMENT

(TOP VIEW)

PIN NU	JMBER	SVMPOL	FUNCTION			
SOT-26	USP-6B	SYMBOL	FUNCTION			
1	6	GND	Ground			
2	5	CE/	Chip Enable (Low Active)			
3	4	C1+	External Capacitor +Pin			
4	3	Vout	Reverse Output			
5	2	Vin	Power Supply			
6	1	C1-	External Capacitor -Pin			

### ■PIN FUNCTIOS ASSIGNMENT

CE/PIN	STATUS
Н	Stand-by
L	Active

# ■ABSOLUTE MAXIMUM RATINGS

			66	Ta = 25°C
PARAMETER	२	SYMBOL	RATINGS	UNITS
Vin Input Volta	ge	Vin	6.0	V
Vout Pin Volta	ge	Vout	-6.0 ~ 0.3	V
C1+ Pin Voltag	ge	C1+	-0.3 ~ VIN + 0.3	V
C1- Pin Voltag	je	C1-	Vout - 0.3 ~ 0.3	V
CE/ Pin Voltag	CE/ Pin Voltage		-0.3 ~ VIN + 0.3	V
VOUT Pin Curre	Vout Pin Current		50	mA
		Pd	150 (IC only)	
Dewer Dissinction	SOT-26		600 (40mm x 40mm Standard board ) (*1)	
Power Dissipation	Power Dissipation		100 (IC only)	mW
USP-6B			1000 (40mm x 40mm Standard board ) <sup>(*1)</sup>	1
Operating Temperatu	re Range	Topr	-30 ~ 80	°C
Storage Temperature	e Range	Tstg	-40 ~ 125	°C

Each rating voltage is based on the GND.

<sup>(\*1)</sup> This is a reference data taken by using the test board. Please see the power dissipation page for the mounting condition.

# ■ELECTRICAL CHARACTERISTICS

fosc=120kHz, Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT
Supply Current	IDD		-	310	520	μA	1
Operating Voltage Range	Vin	$RL=5k\Omega$	1.2	-	5.0	V	2
Oscillation Frequency	fosc		75	120	192	kHz	1
Power Transition Efficiency	EFFI	$RL=2k\Omega$	-	90	-	%	2
Voltage Transition Efficiency	Veffi	RL=∞	95	-	-	%	2
Output Impedance	Rout	$RL=5k\Omega$	-	45	90	Ω	2
Stand -by Current	ISTB	CE/=VIN	-	-	2.0	μA	3
CE/ 'H' Level Voltage	VCEH		0.9	-	-	V	3
CE/ 'L' Level Voltage	VCEL		-	-	0.25	V	3

Measuring Conditions: Unless otherwise stated, VIN = 5.0V, CE/ = 0V

fosc=35kHz, Ta=25°C

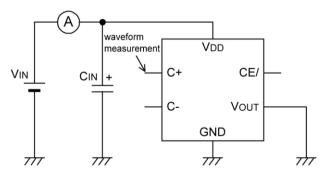
PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT
Supply Current	I <sub>DD</sub>		-	100	170	μA	1
Operating Voltage Range	VIN	$RL=5k\Omega$	1.2	-	5.0	V	2
Oscillation Frequency	fosc		21	35	56	kHz	1
Power Transition Efficiency	EFFI	$RL=2k\Omega$	-	90	-	%	2
Voltage Transition Efficiency	VEFFI	RL=∞	95	-	-	%	2
Output Impedance	Rout	$RL=5k\Omega$	-	45	90	Ω	2
Stand -by Current	Istb	CE/=VIN	-	-	2.0	μA	3
CE/ 'H' Level Voltage	VCEH		0.9	-	-	V	3
CE/ 'L' Level Voltage	VCEL		-	-	0.25	V	3

Measuring Conditions: Unless otherwise stated, VIN = 5.0V, CE/ = 0V

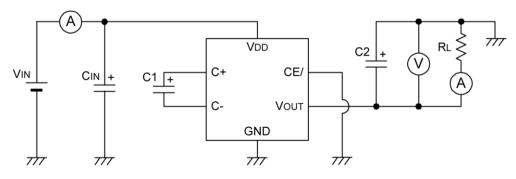
# XC6351A Series

## ■TEST CIRCUITS

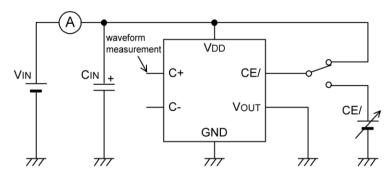
Circuit 1



Circuit 2



Circuit 3

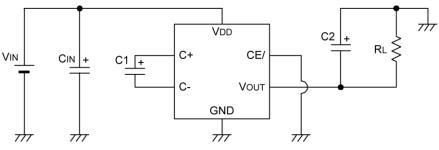


External components:

 $\label{eq:CIN} \begin{array}{l} {\sf CIN}=1\mu{\sf F}\mbox{ (ceramic capacitor)}\\ {\sf C1}={\sf C2}=1\mu{\sf F}\mbox{ (ceramic capacitor)}^*\\ {}^*\mbox{ With the custom 35kHz frequency, C1}={\sf C2}=3.3\mu{\sf F} \end{array}$ 

### ■ TYPICAL APPLICATION CIRCUIT

Standard Circuit



External components:

 $C_{IN} = 1\mu F$  (ceramic capacitor)

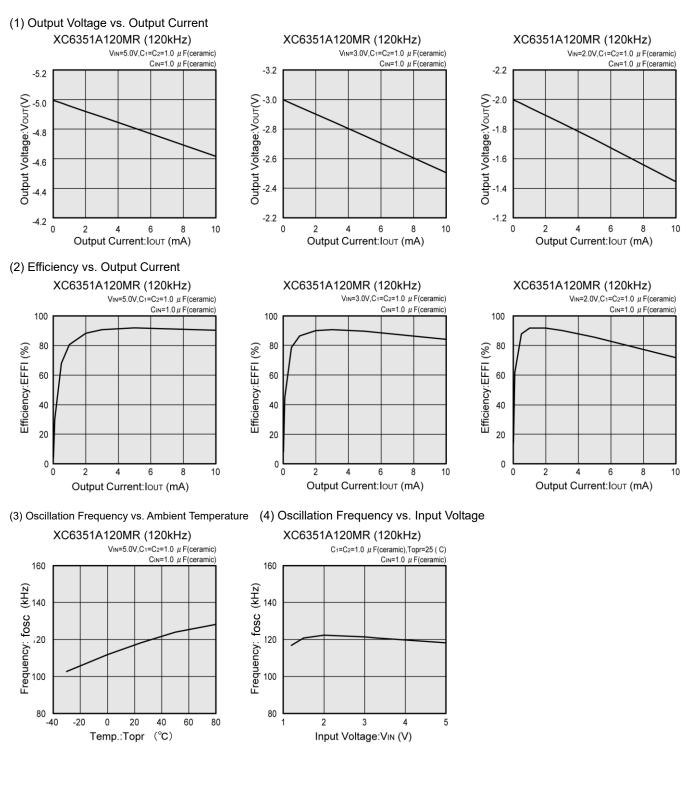
C1 = C2 = 1µF (ceramic capacitor)\*

\* With the custom 35kHz frequency, C1 = C2 = 3.3 µF

## ■ NOTES ON USE

- 1. Please use the IC & external components: within the specified electrical characteristics range and ensure that absolute maximum ratings are not exceeded.
- 2. For C1 & C2, please use a capacitor with as small an ESR value as possible.
- 3. In order to reduce impedance between the IC's input pin and the power supply, we recommend that a capacitor (CIN) be connected to the input side.
- 4. If an external power supply is applied to the output pin in order to have VOUT connected to GND during standby, large current flows through the IC are a possibility. Further, do not use a capacitor at C2 that has a large capacitance value.

# ■TYPICAL PERFORMANCE CHARACTERISTICS



# ■ PACKAGING INFORMATION

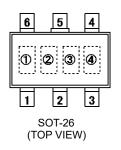
For the latest package information go to, <u>www.torexsemi.com/technical-support/packages</u>

PACKAGE	CKAGE OUTLINE / LAND PATTERN THERMAL CHARACTERISTICS			
SOT-26	SOT-26 PKG	SOT-26 Power Dissipation		
USP-6B	USP-6B PKG	USP-6B Power Dissipation		

# XC6351A Series

## ■MARKING RULE

#### SOT-26



#### ① represents product series

MARK	PRODUCT SERIES	
A	XC6351AxxxMx-G	

#### 2,3 represents oscillation frequency

MA	RK			
2	3	OSCILLATION FREQUENCY	PRODUCT SERIES	
0	3	35kHz	XC6351A035MR-G	
1	2	120kHz	XC6351A120MR-G	

④ represents production lot number

0 to 9, A to Z repeated (G, I, J, O, Q, W excluded)

#### (1,2,3) represents product series

MARK			
1	2	3	PRODUCT SERIES
5	1	A	XC6351AxxxDR-G

#### (4),(5) represents oscillation frequency

M/ ④	ARK 5	OSCILLATION FREQUENCY	PRODUCT SERIES
0	3	35kHz	XC6351A035DR-G
1	2	120kHz	XC6351A120DR-G

#### ⑥ represents production lot number

0 to 9,A to Z repeated (G, I, J, O, Q, W excluded) Note: No character inversion used.

#### ●USP-6B

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